# 

# **General Description**

**Features** 

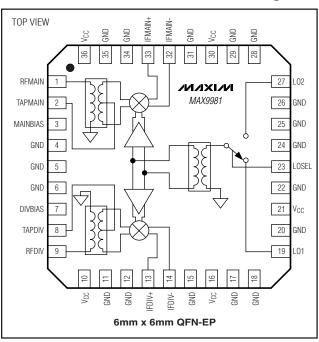
- +27.3dBm Input IP3
- +13.6dBm Input 1dB Compression Point
- 825MHz to 915MHz RF Frequency Range
- 70MHz to 170MHz IF Frequency Range
- ♦ 725MHz to 1085MHz LO Frequency Range
- 2.1dB Conversion Gain
- 10.8dB Noise Figure
- ♦ 42dB Channel-to-Channel Isolation
- ♦ -5dBm to +5dBm LO Drive
- +5V Single-Supply Operation
- Built-In LO Switch with 52dB LO1 to LO2 Isolation
- ESD Protection
- Integrated RF and LO Baluns for Single-Ended Inputs

## **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX9981EGX-T	-40°C to +85°C	36 QFN-EP* (6mm × 6mm)

\*EP = Exposed paddle.

## Pin Configuration/ Functional Diagram



# The MAX9981 dual high-linearity mixer integrates a local oscillator (LO) switch, LO buffer, LO splitter, and two active mixers. On-chip baluns allow for single-ended RF and LO inputs. The active mixers eliminate the need for an additional IF amplifier because the mixer provides a typical overall conversion gain of 2.1dB.

The MAX9981 active mixers are optimized to meet the demanding requirements of GSM850, GSM900, and CDMA850 base-station receivers. These mixers provide exceptional linearity with an input IP3 of greater than +27dBm. The integrated LO driver allows for a wide range of LO drive levels from -5dBm to +5dBm. In addition, the built-in high-isolation switch enables rapid LO selection of less than 250ns, as needed for GSM transceiver designs.

The MAX9981 is available in a 36-pin QFN package ( $6mm \times 6mm$ ) with an exposed paddle, and is specified over the -40°C to +85°C extended temperature range.

## **Applications**

GSM850/GSM900 2G and 2.5G EDGE Base-Station Receivers

Cellular cdmaOne<sup>™</sup> and cdma2000<sup>™</sup> Base-Station Receivers

TDMA and Integrated Digital Enhanced Network (iDEN)™ Base-Station Receivers

Digital and Spread-Spectrum Communication Systems

Microwave Point-to-Point Links

cdmaOne is a trademark of CDMA Development Group.

cdma2000 is a trademark of Telecommunications Industry Association.

iDEN is a trademark of Motorola, Inc.

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# **MAX9981**

## **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> 0.3V to +5.5V	Continuous Power Dissipation (T <sub>A</sub> = +70°C)
IFMAIN+, IFMAIN-, IFDIV+, IFDIV-,	36-Pin QFN (derate 33mW/°C above +70°C)2200mW
MAINBIAS, DIVBIAS, LOSEL0.3V to (V <sub>CC</sub> + 0.3V)	Operating Temperature Range40°C to +85°C
TAPMAIN, TAPDIV+5.5V	Junction Temperature+150°C
MAINBIAS, DIVBIAS Current5mA	Storage Temperature Range65°C to +150°C
RFMAIN, RFDIV, LO1, LO2 Input Power+20dBm	Lead Temperature (soldering, 10s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

(*Typical Application Circuit*,  $V_{CC}$  = +4.75V to +5.25V, no RF signals applied, all RF inputs and outputs terminated with 50 $\Omega$ , 267 $\Omega$  resistors connected from MAINBIAS and DIVBIAS to GND,  $T_A$  = -40°C to +85°C, unless otherwise noted. Typical values are at  $V_{CC}$  = +5.0V,  $T_A$  = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
Supply Voltage	V <sub>CC</sub>		4.75	5.00	5.25	V
Supply Current	Icc		260	291	325	mA
Input High Voltage	VIH		3.5			V
Input Low Voltage	VIL				0.4	V
LOSEL Input Current	ILOSEL		-5		+5	μA

# AC ELECTRICAL CHARACTERISTICS

(*Typical Application Circuit*,  $V_{CC} = +4.75V$  to +5.25V,  $P_{LO} = -5dBm$  to +5dBm,  $f_{RF} = 825MHz$  to 915MHz,  $f_{LO} = 725MHz$  to 1085MHz,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $V_{CC} = +5.0V$ ,  $P_{RF} = -5dBm$ ,  $P_{LO} = 0dBm$ ,  $f_{RF} = 870MHz$ ,  $f_{LO} = 770MHz$ ,  $T_A = +25^{\circ}C$ , unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	MAX	UNITS		
RF Frequency	f <sub>RF</sub>			825		915	MHz		
LO Frequency	fLO			725		1085	MHz		
IF Frequency	fIF	Must meet RF and LO frequency range. IF matching components affect IF frequency range.		70		170	MHz		
LO Drive Level	PLO				-5		+5	dBm	
Conversion Gain (Note 3)	$V_{CC} = +5.0V,$ $f_{IF} = 100MHz,$		Cellular b f <sub>RF</sub> = 825 850MHz	'		2.7		dB	
Conversion Gain (Note 3)	GC	low-side injection $P_{RF} = 0dBm$ , $P_{LO} = -5dBm$	' GSM ban f <sub>RF</sub> = 880 to 915MH	MHz		2.1		uв	
Gain Variation from Nominal		$f_{RF}$ = 825MHz to 915MHz, $3\sigma$			±0.6		dB		
Conversion Loss from LO to IF		Inject $P_{IN} = -20$ dBm at $f_{LO} + 100$ MHz into LO port. Measure 100MHz at IF port as $P_{OUT}$ . No RF signal at RF port.			53		dB		
	NF	100MHz IF,	Cellular band, f <sub>RF</sub> = 825MHz to 85	50MHz		10.8		dB	
Noise Figure		low-side injection	GSM band, f <sub>RF</sub> = 880MHz to 915MHz			11.9			



# AC ELECTRICAL CHARACTERISTICS (continued)

(*Typical Application Circuit*,  $V_{CC}$  = +4.75V to +5.25V,  $P_{LO}$  = -5dBm to +5dBm,  $f_{RF}$  = 825MHz to 915MHz,  $f_{LO}$  = 725MHz to 1085MHz,  $T_A$  = -40°C to +85°C, unless otherwise noted. Typical values are at  $V_{CC}$  = +5.0V,  $P_{RF}$  = -5dBm,  $P_{LO}$  = 0dBm,  $f_{RF}$  = 870MHz,  $f_{LO}$  = 770MHz,  $T_A$  = +25°C, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	С	MIN	ТҮР	MAX	UNITS	
Input 1dB Compression Point	P <sub>1dB</sub>	Low-side injection		13.6			dBm
Input Third-Order Intercept Point	IIP3	$P_{LO} = -5 dBm to$	+5dBm (Notes 3, 4)	27.3			dBm
2 RF - 2 LO Spur Rejection	2×2	$f_{RF} = 915MHz$ , $f_{LO} = 815MHz$ , Main		53.3		dBc	
	2 ~ 2	f <sub>SPUR</sub> = 865MHz	, P <sub>RF</sub> = -5dBm Diversity	43.2		UBC	
3 RF - 3 LO Spur Rejection	3×3	$f_{RF} = 915MHz$ , $f_{L}$ $f_{SPUR} = 848.3MH$		79.7			dBc
Maximum LO Leakage at RF Port		$\begin{array}{l} P_{LO} = -5 dBm \mbox{ to } +5 dBm, \\ f_{LO} = 725 MHz \mbox{ to } 1100 MHz \end{array} \qquad -42 \end{array}$			dBm		
Maximum LO Leakage at IF Port		$P_{LO} = -5dBm$ to +5dBm, f <sub>LO</sub> = 725MHz to 1100MHz		-30.6			dBm
Minimum RF to IF Isolation		$P_{LO} = -5dBm$ to +5dBm, f <sub>RF</sub> = 825MHz to 915MHz		18		dB	
LO1 to LO2 Isolation		f <sub>RF</sub> = 825MHz to 915MHz, P <sub>LO1</sub> = P <sub>LO2</sub> = +5dBm, f <sub>IF</sub> = 100MHz (Note 5)			52		dB
		f <sub>RF</sub> = 825MHz to 915MHz,	$P_{RFMAIN} = -5dBm, RFDIV$ terminated with $50\Omega$ . Measured power at IFDIV relative to IFMAIN.		39.5		j
Minimum Channel Isolation		$f_{LO} = 725MHz$ to 1085MHz	$P_{RFDIV} = -5dBm, RFMAIN$ terminated with $50\Omega$ . Measured power at IFMAIN relative to IFDIV.		42		dBc
LO Switching Time		50% of LOSEL to IF settled within 2°			250		ns
RF Return Loss				25			dB
		LO port selected		19		dD	
LO Return Loss		LO port unselected		14.3		dB	
IF Return Loss		RF and LO terminated into $50\Omega$ , f <sub>IF</sub> = 100MHz (Note 6)		· 15			dB

Note 1: Guaranteed by design and characterization.

**Note 2:** All limits reflect losses of external components. Output measurements taken at IF OUT of *Typical Application Circuit*. **Note 3:** Production tested.

Note 4: Two tones at 1MHz spacing, -5dBm per tone at RF port.

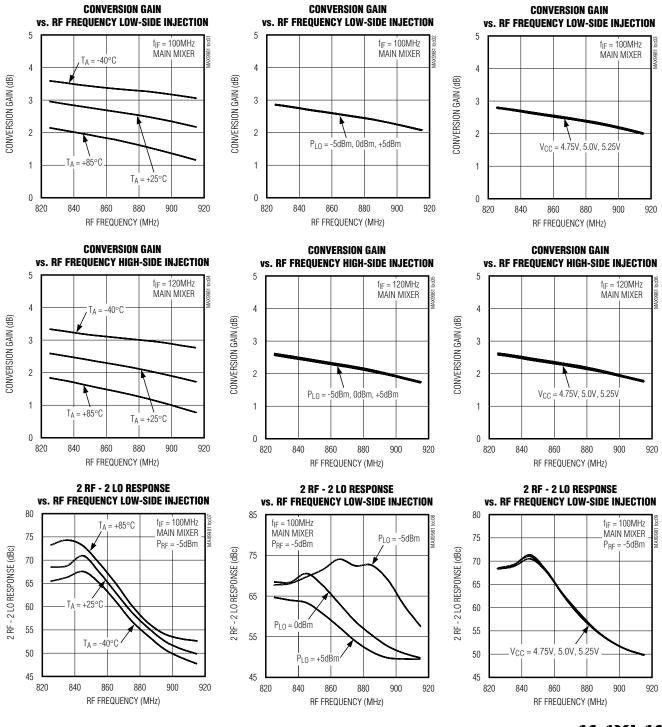
Note 5: Measured at IF port at IF frequency.  $f_{LO1}$  and  $f_{LO2}$  are offset by 1MHz.

Note 6: IF return loss can be optimized by external matching components.

(Typical Application Circuit, V<sub>CC</sub> = 5.0V, P<sub>RF</sub> = -5dBm, P<sub>LO</sub> = 0dBm, T<sub>A</sub> = +25°C, unless otherwise noted.)

**Typical Operating Characteristics** 

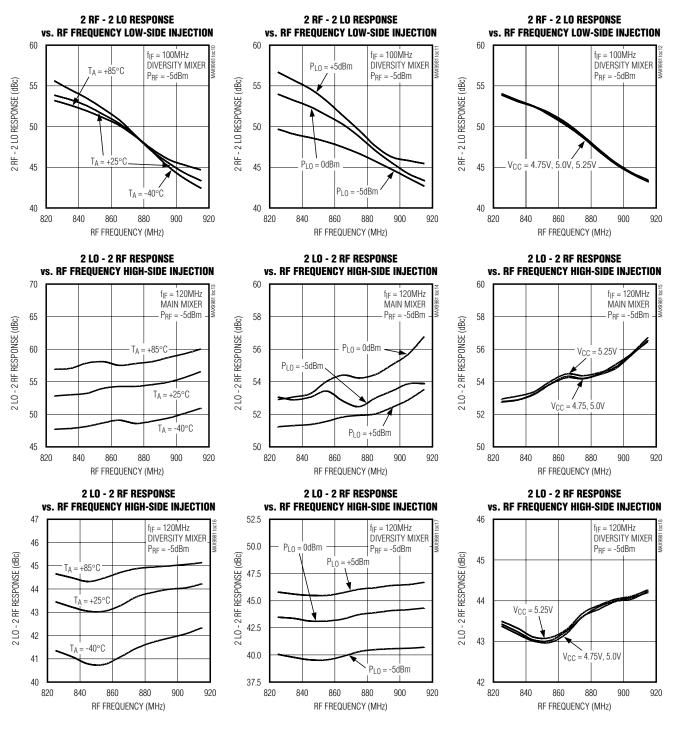
**MAX9981** 



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## \_Typical Operating Characteristics (continued)

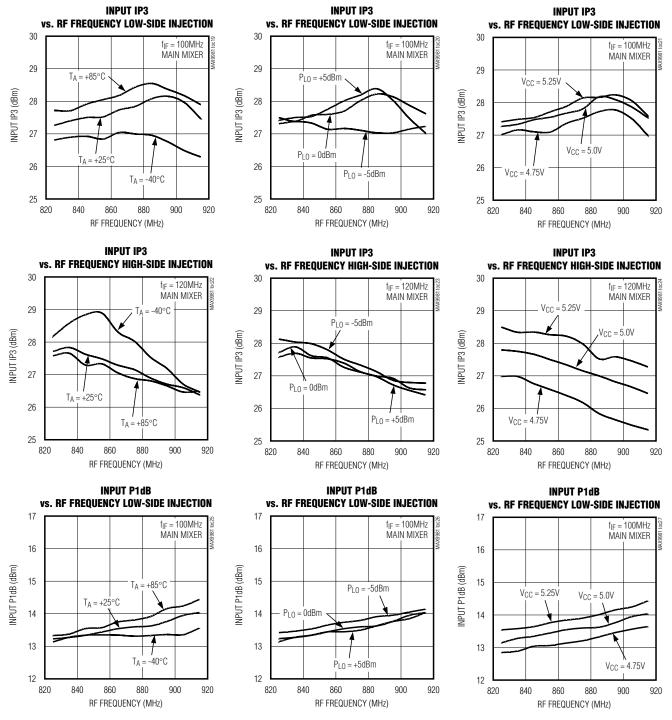
(Typical Application Circuit, V<sub>CC</sub> = 5.0V, P<sub>RF</sub> = -5dBm, P<sub>LO</sub> = 0dBm, T<sub>A</sub> = +25°C, unless otherwise noted.)





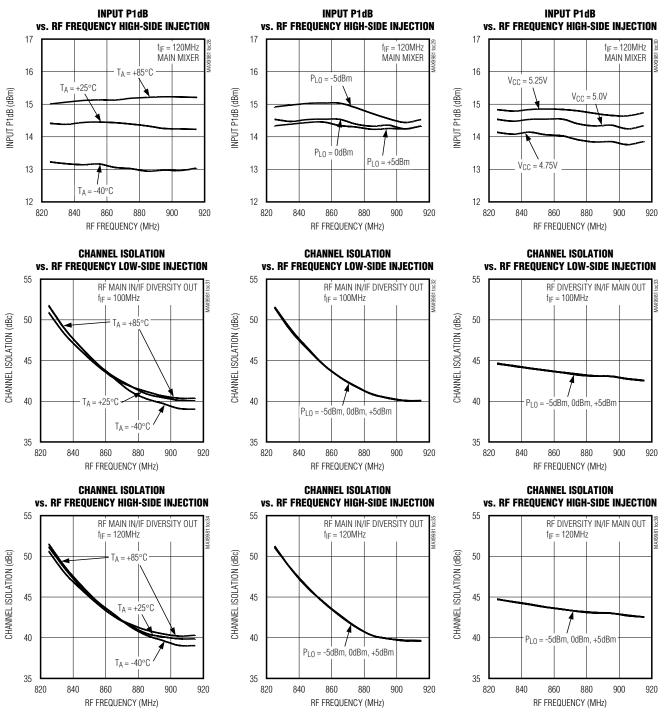
# \_\_\_\_Typical Operating Characteristics (continued)

(Typical Application Circuit, V<sub>CC</sub> = 5.0V, P<sub>RF</sub> = -5dBm, P<sub>LO</sub> = 0dBm, T<sub>A</sub> = +25°C, unless otherwise noted.)



## \_Typical Operating Characteristics (continued)

(Typical Application Circuit, V<sub>CC</sub> = 5.0V, P<sub>RF</sub> = -5dBm, P<sub>LO</sub> = 0dBm, T<sub>A</sub> = +25°C, unless otherwise noted.)



(Typical Application Circuit, V<sub>CC</sub> = 5.0V, P<sub>RF</sub> = -5dBm, P<sub>LO</sub> = 0dBm, T<sub>A</sub> = +25°C, unless otherwise noted.)

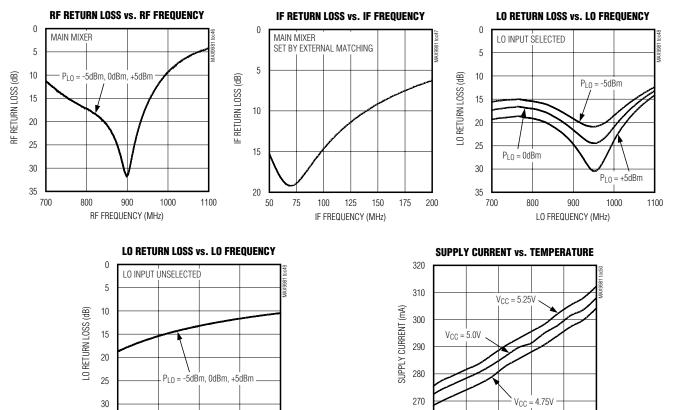
**Typical Operating Characteristics (continued)** 



### LO SWITCH ISOLATION LO SWITCH ISOLATION LO SWITCH ISOLATION vs. RF FREQUENCY LOW-SIDE INJECTION vs. RF FREQUENCY LOW-SIDE INJECTION vs. RF FREQUENCY HIGH-SIDE INJECTION 56 56 56 LO OFFSET 1MHz LO OFFSET 1MHz LO OFFSET 1MHz $f_{IF} = 100 MHz$ f<sub>IF</sub> = 100MHz f<sub>IF</sub> = 120MHz MAIN MIXER $P_{L0} = -5dBm$ DIVERSITY MIXER-DIVERSITY MIXER 55 55 55 +85°C LO SWITCH ISOLATION (dBc) LO SWITCH ISOLATION (dBc) LO SWITCH ISOLATION (dBc) 54 +85°( 54 54 53 53 53 $T_A = +25^{\circ}C$ $P_{L0} = 0 dBm$ 52 -40°C 52 52 TΔ $\dot{P}_{L0} = +5 d\dot{B}m$ -40°C $T_{\Lambda} = +25^{\circ}C$ ΤA 51 51 51 820 840 880 920 820 860 900 920 820 840 880 920 860 900 840 880 860 900 RF FREQUENCY (MHz) RF FREQUENCY (MHz) RF FREQUENCY (MHz) LO LEAKAGE AT IF PORT LO LEAKAGE AT IF PORT LO LEAKAGE AT RF PORT vs. LO FREQUENCY vs. LO FREQUENCY vs. LO FREQUENCY -30 -27 -40 MAIN MIXER MAIN MIXER MAIN MIXER $P_{L0} = -5dBm$ $T_A = +85^{\circ}C$ -45 -33 -30 $\mathsf{P}_{L0} = 0 dBm$ -50 LO LEAKAGE (dBm) LO LEAKAGE (dBm) LO LEAKAGE (dBm) $P_{L0} = +5dBm$ +25°C -36 -33 -55 -39 -36 $P_{L0} = 0 dBm$ -60 $T_A = -40^{\circ}C$ -42 -39 -65 $P_{L0} = +5dBm$ $P_{LO} = -5dBm$ -45 -42 -70 800 850 900 950 1000 750 750 800 850 900 950 1000 700 800 900 1000 1100 LO FREQUENCY (MHz) LO FREQUENCY (MHz) LO FREQUENCY (MHz) **RF TO IF ISOLATION RF TO IF ISOLATION NOISE FIGURE** vs. RF FREQUENCY vs. RF FREQUENCY vs. RF FREQUENCY LOW-SIDE INJECTION 30 26 15 $f_{IF} = 100 MHz$ MAIN MIXER MAIN MIXER MAIN MIXER 14 27 24 RF T0 IF ISOLATION (dB) RF TO IF ISOLATION (dB) 13 $T_A = +85^{\circ}C$ NOISE FIGURE (dB) $P_{LO} = 0 dBm, +5 dBm$ 24 Г<sub>А</sub> = +85°С 12 22 11 Ta = +25° 21 10 +25°C 20 18 $T_A = -40^\circ$ 9 -40°C T<sub>A</sub> = $P_{L0} = -5dBm$ 18 15 8 820 820 840 860 880 900 920 840 860 880 900 920 820 840 860 880 900 920 RF FREQUENCY (MHz) RF FREQUENCY (MHz) RF FREQUENCY (MHz)

# \_Typical Operating Characteristics (continued)

(*Typical Application Circuit*,  $V_{CC}$  = 5.0V,  $P_{RF}$  = -5dBm,  $P_{LO}$  = 0dBm,  $T_A$  = +25°C, unless otherwise noted.)



260

-40

-15

10

TEMPERATURE (°C)

35

60

85

# MAX9981

35

700

800

900

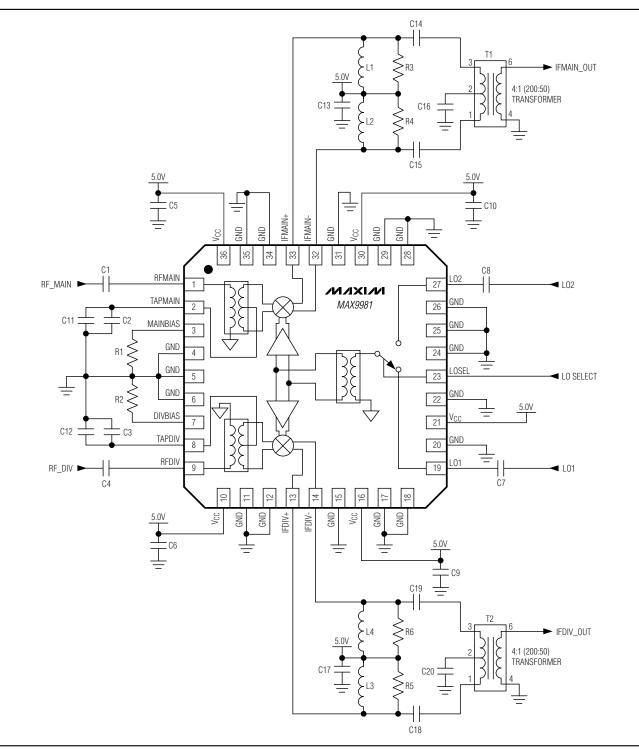
LO FREQUENCY (MHz)

1000

MAX9981

		Pin Description
PIN	NAME	FUNCTION
1	RFMAIN	Main Channel RF Input. This input is internally matched to $50\Omega$ and is DC shorted to ground through a balun.
2	TAPMAIN	Main RF Balun Center Tap. Connect bypass capacitors from this pin to ground.
3	MAINBIAS	Bias control for the Main Mixer. Connect a $267\Omega$ resistor from this pin to ground to set the bias current for the main mixer.
4, 5, 6, 11, 12, 15, 17, 18, 20, 22, 24, 25, 26, 28, 29, 31, 34, 35, EP	GND	Ground
7	DIVBIAS	Bias Control for the Diversity Mixer. Connect a $267\Omega$ resistor from this pin to ground to set the bias current for the diversity mixer.
8	TAPDIV	Diversity RF Balun Center Tap. Connect bypass capacitors from this pin to ground.
9	RFDIV	Diversity Channel RF Input. This input is internally matched to $50\Omega$ and is DC shorted to ground through a balun.
10, 16, 21, 30, 36	V <sub>CC</sub>	Power-Supply Connections. Connect bypass capacitors as shown in the <i>Typical Application Circuit</i> .
13, 14	IFDIV+, IFDIV-	Differential IF Output for Diversity Mixer. Connect 560nH pullup inductors and $137\Omega$ pullup resistors from each of these pins to V <sub>CC</sub> for a 70MHz to 100MHz IF range.
19	LO1	Local Oscillator Input 1. This input is internally matched to $50\Omega$ and is DC shorted to ground through a balun.
23	LOSEL	Local Oscillator Select. Set this pin to logic HIGH to select LO1; set to logic LOW to select LO2.
27	LO2	Local Oscillator Input 2. This input is internally matched to $50\Omega$ and is DC shorted to ground through a balun.
32, 33	IFMAIN-, IFMAIN+	Differential IF Output for the Main Mixer. Connect 560nH pullup inductors and 137 $\Omega$ pullup resistors from each of these pins to V <sub>CC</sub> for a 70MHz to 100MHz IF range.

# **Typical Application Circuit**



MAX9981

# \_Component List

COMPONENT	VALUE	SIZE	PART NUMBER
C1, C4	33pF	0603	Murata GRM1885C1H330J
C2, C3	3.9pF	0603	Murata GRM1885C1H3R9C
C5, C6, C9, C10	100pF	0603	Murata GRM1885C1H101J
C7, C8	15pF	0603	Murata GRM1885C1H150J
C11, C12	0.033µF	0603	Murata GRM188R71E333K
C13, C16, C17, C20	220pF	0603	Murata GRM1885C1H221J
C14, C15, C18, C19	330pF	0603	Murata GRM1885C1H331J
L1–L4	560nH	1008	CoilCraft 1008CS-561XJBB
R1, R2	267Ω ±1%	0603	—
R3–R6	137Ω ±1%	0603	—
T1, T2	4:1 (200:50)	—	Mini-Circuits TC4-1W-7A

## **Detailed Description**

The MAX9981 downconverter mixers are designed for GSM and CDMA base-station receivers with an RF frequency between 825MHz and 915MHz. Each active mixer provides 2.1dB to 2.7dB of overall conversion gain to the receive signal, removing the need for an external IF amplifier. The mixers have excellent input IP3 measuring greater than +27dBm. The device also features integrated RF and LO baluns that allow the mixers to be driven with single-ended signals.

# **RF Inputs**

**LO Inputs** 

The MAX9981 has two RF inputs (RFMAIN, RFDIV) that are internally matched to  $50\Omega$  requiring no external matching components. A 33pF DC-blocking capacitor is required at the input since the input is internally DC shorted to ground through a balun. Return loss is better than 15dB over the entire frequency range of 825MHz to 915MHz.

The mixers can be used for either high-side or low-side injection applications with an LO frequency range of 725MHz to 1085MHz. An internal LO switch allows for switching between two single-ended LO ports. This is useful for fast frequency changes/frequency hopping. LO switching time is less than 250ns. The switch is controlled by a digital input (LOSEL) that when high, selects LO1

with both RFMAIN and RFDIV to produce the IF signals. Internal LO buffers allow for a wide power range on the LO ports. The LO signal power can vary from -5dBm to +5dBm. LO1 and LO2 are internally matched to  $50\Omega$ , so only a 15pF DC-blocking capacitor is required at each LO port.

and when low, selects LO2. The selected LO input mixes

## **IF Outputs**

Each mixer has an IF frequency range of 70MHz to 170MHz. The differential IF output ports require external pullup inductors to V<sub>CC</sub> to resonate out the differential on-chip capacitance of 1.8pF. See the *Typical Application Circuit* for recommended component values for an IF of 70MHz to 100MHz. The IF match can be optimized for higher IF frequencies by reducing the values of the pullup inductors L1, L2, L3, and L4. **Note:** Removing the ground plane from underneath these inductors reduces parasitic capacitive loading and improves VSWR.

## **Bias Circuitry**

Connect bias resistors from MAINBIAS and DIVBIAS to ground to set the mixer bias current. A nominal resistor value of  $267\Omega$  sets an input IP3 of +27dBm and supply current of 290mA. Bias currents are fine-tuned at the factory and should not be adjusted.

## Applications Information

## **Layout Considerations**

A properly designed PC board is an essential part of any RF/microwave circuit. Keep RF signal lines as short as possible to reduce losses, radiation, and inductance. For best performance, route the ground pin traces directly to the exposed paddle underneath the package. This paddle should be connected to the ground plane of the board by using multiple vias under the device to provide the best RF/thermal conduction path. Solder the exposed paddle, on the bottom of the device package, to a PC board exposed pad.



## **Power Supply Bypassing**

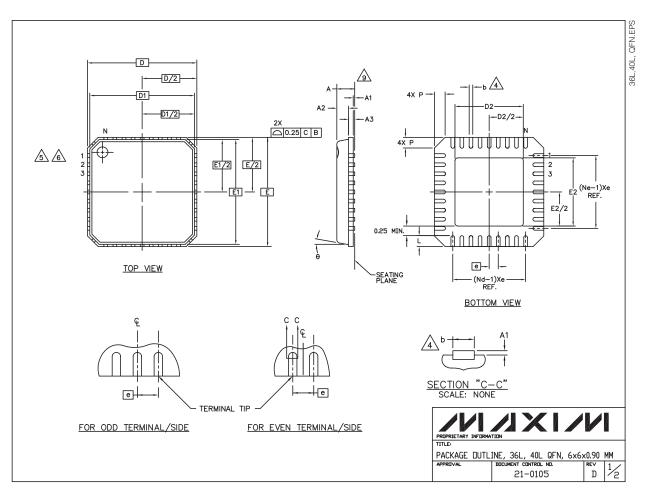
Proper voltage supply bypassing is essential for high-frequency circuit stability. Bypass each V<sub>CC</sub> pin, TAPMAIN, and TAPDIV with the capacitors shown in the typical application circuit. Place the TAPMAIN and TAPDIV bypass capacitors to ground within 100mils of the TAPMAIN and TAPDIV pins.

## **Chip Information**

TRANSISTOR COUNT: 358 PROCESS: BICMOS

## **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



# Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)

NOTES:	
<ol> <li>DIE THICKNESS ALLOWABLE IS 0.305mm MAXIMUM (.012 INCHES MAXIMUM)</li> <li>DIMENSIONING &amp; TOLERANCES CONFORM TO ASME Y14.5M 1994.</li> <li>N IS THE NUMBER OF TERMINALS. N X-DIRECTION &amp; Nd IS THE NUMBER OF TERMINALS IN X-DIRECTION.</li> <li>DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25mm FROM TERMINAL TIP.</li> <li>THE PIN #1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR INK/LASER MARKED.</li> <li>EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.</li> <li>ALL DIMENSIONS ARE IN MILLIMETERS.</li> <li>PACKAGE WARPAGE MAX 0.05mm.</li> <li>APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING.</li> <li>MEETS JEDEC M0220.</li> <li>THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STRAIGHT SIDES) QFN STYLES.</li> </ol>	$\begin{array}{c c c c c c c c c c c c c c c c c c c $
PITCH VARIATION C	
PITCH         VARIATION         C           0         MIN.         NOM.         MAX.         Not relation         MIN.         NOM.         MAX.           Image: Constraint of the state	
	PROPRIETARY INFORMATION TITLE PACKAGE DUTLINE, 36L, 40L QFN, 6x6x0.90 MM APPROVAL DOCUMENT CONTROL NO. 21-0105 D

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